

NOTE 3

e2|-

e3

SIP25, 5.72x3.18 CASE 127DZ ISSUE A

DATE 06 DEC 2019

DIMENSIONING AND TOLERANCING PER

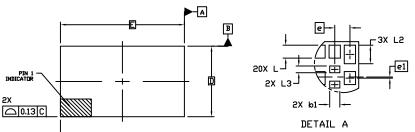
CONTROLLING DIMENSION: MILLIMETERS

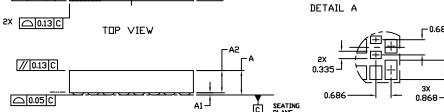
COPLANARITY APPLIES TO THE SPHERICAL

ASME Y14.5M, 1994.

CROWNS OF THE PADS.

MILLIMETERS

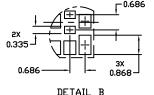


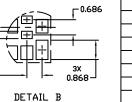


DETAIL A

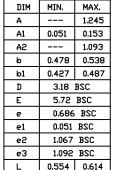
e/2

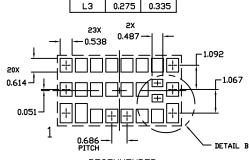
SEATING PLANE Ċ





NUTES:





0.808

0.868

L2

RECOMMENDED MOUNTING FOOTPRINT

additional information on our Pb-Fr tegy and soldering detalls, please IN Semiconductor Soldering and Mou niques Reference Manual, SDLDERRM

23X b Ф 0.05 C A B 0.03 C BOTTOM VIEW BOTTOM VIEW PIN LAYOUT

SIDE VIEW

e

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code ZZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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